



JST16E



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ELECTRICAL CHARACTERISTICS ($T_j=25$ unless otherwise specified)

Symbol	Test Condition	Quadrant	Value		Unit
I_{GT}	$V_D=12V$ $R_L=33$	- -	MAX.	25	mA

ORDERING INFORMATION

<u>J</u>	<u>ST</u>	<u>16</u>	<u>E</u>	<u>-800</u>	<u>C</u>	<u>-/</u>
JieJie Microelectronics Co., Ltd.	Triacs	$I_{T(RMS)}: 16A$	<u>E: TO-263</u>	<u>800: $V_{DRM} / V_{RRM} \quad 800V$</u>	<u>C: $I_{GT1-3} \quad 25mA \quad I_{GT4} \quad 50mA$</u>	Blank: Tube -TR: Tape & Reel

MARKING

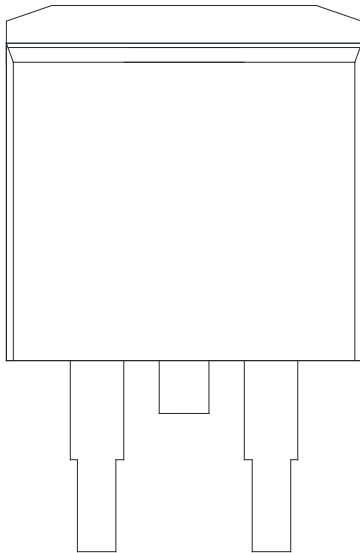


FIG.7: Relative variations of gate trigger current, holding current and latching current versus junction temperature

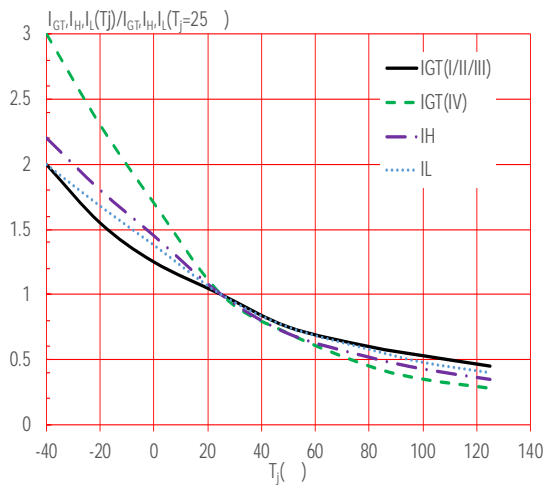
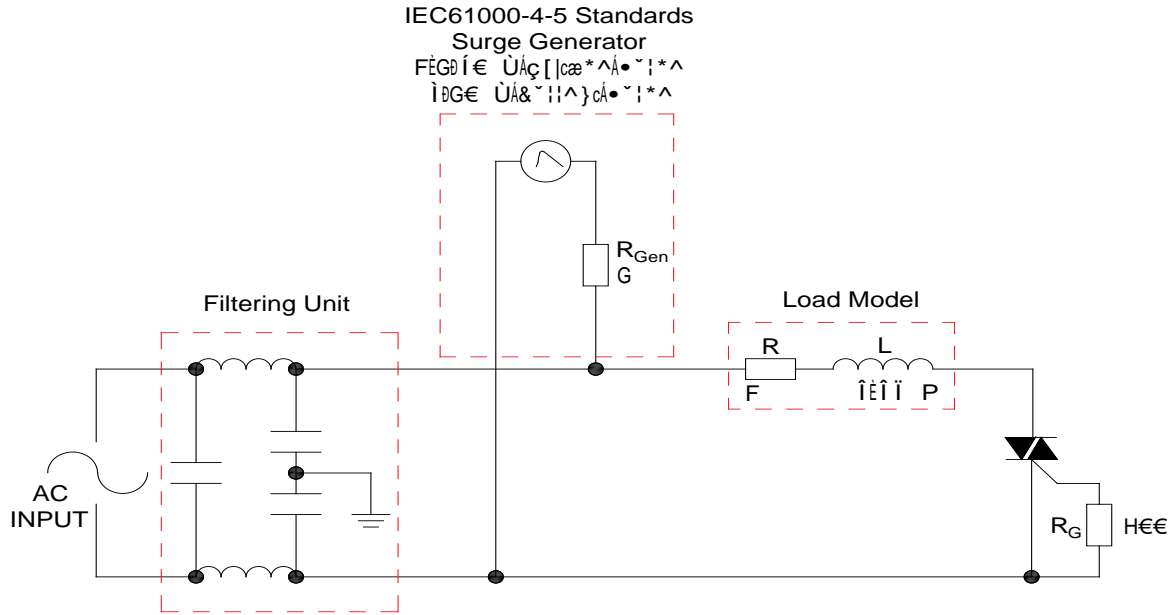


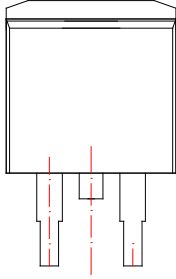
FIG.8: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3 /sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)
Time within 5 of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T_p)		8 min. Max
Do not exceed		+260

PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.40		9.60	0.370		0.378
D	2.40			0.094		
E	1.20		1.50	0.047		0.059
F	0.75		0.85	0.029		0.033

DELIVERY MODE



